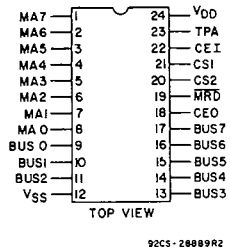


T-46-13-15

CDP1833, CDP1833C, CDP1833BC



CMOS 1024-Word x 8-Bit Static Read-Only Memory

Features:

- CDP1833BC is compatible with the CDP1802BC 5 MHz microprocessor
- On-chip address latch
- Interfaces with CDP1800-series microprocessors without additional components
- Optional programmable location within 64K memory space
- Three-state outputs

TERMINAL ASSIGNMENT

The RCA-CDP1833, CDP1833C, and CDP1833BC are static 8192-bit mask-programmable CMOS read-only memories organized as 1024-words x 8 bits and are completely static; no clocks are required. They will directly interface with the CDP1800-series microprocessors without additional components.

The CDP1833, CDP1833C, and CDP1833BC respond to a 16-bit address multiplexed on 8 address lines. Address latches are provided on-chip to store the 8 most significant bits of the 16-bit address. By mask option, this ROM can be programmed to operate in any 1024-word block within 64K memory space. The polarity of the high-address strobe (TPA), CEI, CS1, and CS2 are user mask-programmable.

The Chip-Enable output signal (CEO) is "high" when the device is selected. Terminals CEO and CEI can be

connected in a daisy chain to control selection of RAM memory in a microprocessor system without additional components.

The CDP1833C and CDP1833BC are functionally identical to the CDP1833. The CDP1833 has a recommended operating voltage range of 4 to 10.5 volts, and the CDP1833C and CDP1833BC have a recommended operating voltage range of 4 to 6.5 volts. The CDP1833BC is designed to interface with the CDP1802BC microprocessor.

The CDP1833, CDP1833C, and CDP1833BC are supplied in 24-lead hermetic dual-in-line side-brazed ceramic package (D suffix) and 24-lead dual-in-line plastic package (E suffix). The CDP1833C is also available in chip form (H suffix).

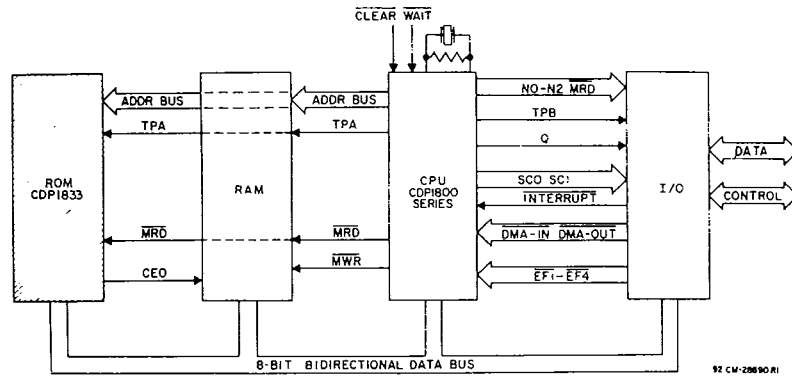


Fig. 1 - Typical CDP1800 Series microprocessor system.

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CDP1833, CDP1833C, CDP1833BC

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MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
(Voltage referenced to V_{SS} terminal)

CDP1833 -0.5 to +11 V
CDP1833C, CDP1833BC -0.5 to +7 V

INPUT VOLTAGE RANGE, ALL INPUTS -0.5 to V_{DD} +0.5 V

DC INPUT CURRENT, ANY ONE INPUT ±10 mA

POWER DISSIPATION PER PACKAGE (P_D):

For T_A = -40 to +60°C (PACKAGE TYPE E) 500 mW
For T_A = +60 to +85°C (PACKAGE TYPE E) Derate Linearly at 12 mW/°C to 200 mW
For T_A = -55 to +100°C (PACKAGE TYPE D) 500 mW
For T_A = +100 to 125°C (PACKAGE TYPE D) Derate Linearly at 12 mW/°C to 200 mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

For T_A = FULL PACKAGE-TEMPERATURE RANGE (All Packages) 100 mW

OPERATING-TEMPERATURE RANGE (T_A):

PACKAGE TYPE D -55 to +125°C
PACKAGE TYPE E -40 to +85°C

STORAGE TEMPERATURE RANGE (T_{stg}) -65 to +150°C

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 ± 1/32 in. (1.59 ± 0.79 mm) from case for 10 s max. +265°C

OPERATING CONDITIONS at T_A = -40° to +85° C

For maximum reliability, operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS				UNITS
	CDP1833		CDP1833C, CDP1833BC		
	Min.	Max.	Min.	Max.	
DC Operating Voltage Range	4	10.5	4	6.5	V
Input Voltage Range	V _{SS}	V _{DD}	V _{SS}	V _{DD}	

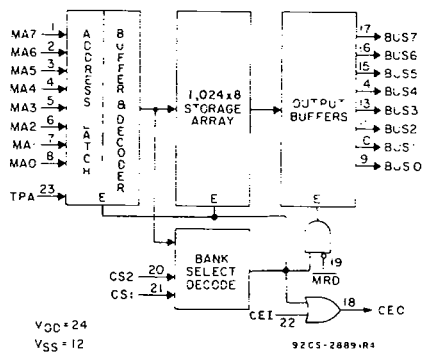


Fig. 2 - Functional diagram.

CDP1833, CDP1833C, CDP1833BC

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STATIC ELECTRICAL CHARACTERISTICS at $T_A = -40$ to $+85^\circ\text{C}$, $V_{DD} \pm 5\%$, Except as noted

CHARACTERISTIC	CONDITIONS			LIMITS						UNITS
	V_O (V)	V_{IN} (V)	V_{DD} (V)	CDP1833			CDP1833C, CDP1833BC			
				Min.	Typ.*	Max.	Min.	Typ.*	Max.	
Quiescent Device Current I_{DD}	—	5	5	—	0.01	50	—	0.02	200	μA
	—	10	10	—	1	200	—	—	—	
Output Low Drive (Sink) Current I_{OL}	0.4	0.5	5	0.8	—	—	0.8	—	—	mA
	0.5	0, 10	10	1.8	—	—	—	—	—	
Output High Drive (Source) Current I_{OH}	4.6	0, 5	5	-0.8	—	—	-0.8	—	—	mA
	9.5	0, 10	10	-1.8	—	—	—	—	—	
Output Voltage Low-Level V_{OL}	—	0, 5	5	—	0	0.1	—	0	0.1	V
	—	0, 10	10	—	0	0.1	—	—	—	
Output Voltage High Level V_{OH}	—	0, 5	5	4.9	5	—	4.9	5	—	V
	—	0, 10	10	9.9	10	—	—	—	—	
Input Low Voltage V_{IL}	0.5, 4.5	—	5	—	—	1.5	—	—	1.5	V
	1, 9	—	10	—	—	3	—	—	—	
Input High Voltage V_{IH}	0.5, 4.5	—	5	3.5	—	—	3.5	—	—	V
	1, 9	—	10	7	—	—	—	—	—	
Input Leakage Current I_{IN}	Any	0, 5	5	—	$\pm 10^{-4}$	± 1	—	$\pm 10^{-4}$	± 1	μA
	Input	0, 10	10	—	$\pm 10^{-4}$	± 2	—	—	—	
3-State Output Current I_{OUT}	0, 5	0, 5	5	—	$\pm 10^{-4}$	± 1	—	$\pm 10^{-4}$	± 1	μA
	0, 10	0, 10	10	—	$\pm 10^{-4}$	± 2	—	—	—	
Operating Device Current I_{DD1}^\dagger	—	0, 5	5	—	7	10	—	7	10	mA
	—	0, 10	10	—	14	20	—	—	—	
Input Capacitance C_{IN}	—	—	—	—	5	7.5	—	5	7.5	pF
Output Capacitance C_{OUT}	—	—	—	—	10	15	—	10	15	pF

* Typical values are for $T_A = 25^\circ\text{C}$ and nominal V_{DD} .

† Outputs open-circuit; cycle time = $2.5 \mu\text{s}$.

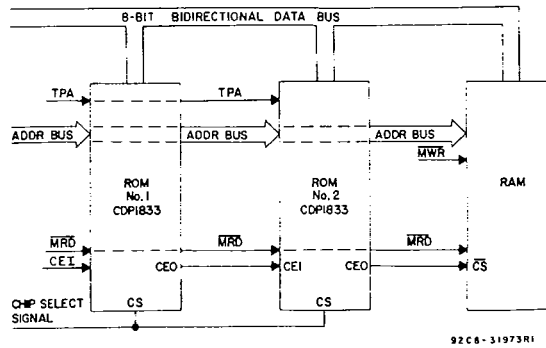


Fig. 3 - Daisy chaining CDP1833's.

"Daisy Chaining" with CEI inputs and CEO outputs is used to avoid memory conflicts between ROM and RAM in a user system. In the above configuration, if ROM #1 was masked-programmed for memory locations 0000-03FF₁₆ and ROM

#2 masked-programmed for memory locations 0400₁₆-07FF₁₆, for address from 0000-07FF₁₆ the RAM would be disabled and the ROM enabled. For locations above 07FF₁₆ the ROM's would be disabled and the RAM enabled.

CDP1833, CDP1833C, CDP1833BC

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = -40$ to 85°C , $V_{DD} \pm 5\%$,
Input $t_r, t_f = 10$ ns, $C_L = 50$ pF, $R_L = 200$ k Ω

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CHARACTERISTIC	TEST CONDITIONS	LIMITS									UNITS	
		CDP1833			CDP1833C			CDP1833BC				
		Min.#	Typ.*	Max.	Min.#	Typ.*	Max.	Min.#	Typ.*	Max.		
Access Time From Address Change t_{AA}	V_{DD} (V)	5	—	650	775	—	650	775	—	575	700	ns
		10	—	350	425	—	—	—	—	—	—	
Access Time From Chip Select t_{ACS}	V_{DD} (V)	5	—	500	625	—	500	625	—	475	600	
		10	—	275	310	—	—	—	—	—	—	
Chip Select Delay t_{CS}	V_{DD} (V)	5	—	250	320	—	250	320	—	250	320	
		10	—	125	180	—	—	—	—	—	—	
Address Setup Time t_{AS}	V_{DD} (V)	5	75	50	—	75	50	—	75	50	—	
		10	40	25	—	—	—	—	—	—	—	
Address Hold Time t_{AH}	V_{DD} (V)	5	100	75	—	100	75	—	75	50	—	
		10	50	30	—	—	—	—	—	—	—	
Read Delay t_{MRD}	V_{DD} (V)	5	—	400	500	—	400	500	—	400	500	
		10	—	200	275	—	—	—	—	—	—	
Chip Enable Output Delay from Address t_{CA}	V_{DD} (V)	5	—	120	170	—	120	170	—	120	170	
		10	—	70	100	—	—	—	—	—	—	
Bus Contention Delay t_D	V_{DD} (V)	5	—	220	270	—	220	270	—	220	270	
		10	—	130	150	—	—	—	—	—	—	
TPA Pulse Width t_{PAW}	V_{DD} (V)	5	200	—	—	200	—	—	175	—	—	
		10	70	—	—	—	—	—	—	—	—	
Chip Enable In to Chip Enable Out Delay t_{CEO}	V_{DD} (V)	5	—	200	250	—	200	250	—	200	250	
		10	—	100	150	—	—	—	—	—	—	

6

Time required by a limit device to allow for the indicated function.

• Time required by a typical device to allow for the indicated function. Typical values are for $T_A = 25^\circ\text{C}$ and nominal voltages.

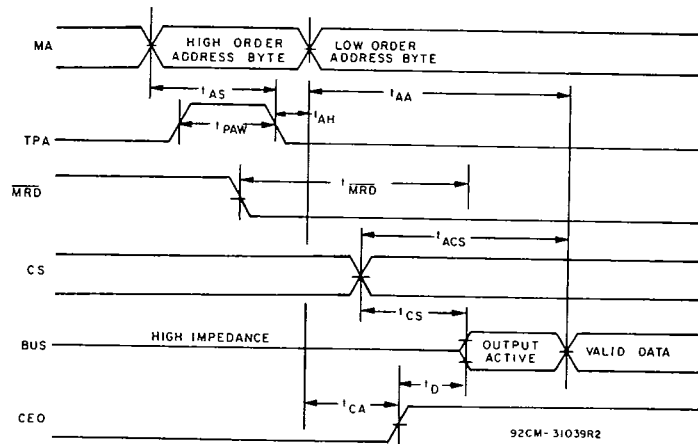


Fig. 4 - Timing waveforms.

Read-Only Memories (ROMs)

T-46-13-15

CDP1833, CDP1833C, CDP1833BC

Note:

The dynamic characteristics and timing diagrams indicate maximum performance capability of the CDP1833. When used directly with a CDP1800-series microprocessor, timing will be determined by the clock frequency and internal delays of the microprocessor.

The following general timing relationships will hold when the CDP1833 is used with a CDP1800-series microprocessor.

$$t_{AH} = 0.5 t_c$$
$$t_{PAW} = 1 t_c$$

\overline{MRD} occurs one clock period (t_c) earlier than the address bits MA0-MA7.

$$\text{where } t_c = \frac{1}{\text{CPU clock frequency}}$$